

Description

The STD10PF06 uses advanced trench

technology to provide excellent $R_{\text{DS}(\text{ON})}$, low gate

charge and operation with gate voltages as low

as 4.5V. This device is suitable for use as a

Battery protection or in other Switching application.

General Features

V_{DS} = -60V I_D =-10 A

 $R_{DS(ON)} < 140 m\Omega @ V_{GS} = 10V$

Application

Brushless motor

Load switch

Uninterruptible power supply

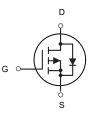
Package Marking and Ordering Information

| Product ID | Pack | Brand | Qty(PCS) |
|------------|-----------|------------|----------|
| STD10PF06 | TO-252-2L | HXY MOSFET | 2500 |

Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

| Symbol | Parameter Rating | | Units |
|---------------------------------------|---|---|-------|
| Vds | Drain-Source Voltage | -60 | V |
| Vgs | Gate-Source Voltage | ±20 | V |
| I⊳@Tc=25°C | Continuous Drain Current, V _{GS} @ -10V ¹ | -10 | А |
| I _D @T _C =100°C | Continuous Drain Current, V _{GS} @ -10V ¹ | rain Current, V_{GS} @ -10V ¹ -8.3 | |
| Ідм | Pulsed Drain Current ² | -26 | А |
| EAS | Single Pulse Avalanche Energy ³ | Single Pulse Avalanche Energy ³ 29.8 | |
| las | Avalanche Current | Avalanche Current -24.4 | |
| P _D @T _C =25°C | Total Power Dissipation ⁴ | 31.3 | W |
| Тѕтс | Storage Temperature Range | -55 to 150 | °C |
| TJ | Operating Junction Temperature Range | -55 to 150 | °C |
| Reja | Thermal Resistance Junction-Ambient ¹ | 62 | °C/W |
| Rejc | Thermal Resistance Junction-Case ¹ | 4.0 °C/W | |





P-Channel MOSFET



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit | |
|---|---|--|---------|--------|------|-------|--|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V , I _D =-250uA | -60 | | | V | |
| $\triangle BV_{\text{DSS}} / \triangle T$ | BV _{DSS} Temperature Coefficient | Reference to 25° C , I _D =-1mA | | -0.049 | | V/°C | |
| 5 | Statio Drain Source On Desistance ² | V _{GS} =-10V , I _D =-8A | 125 140 | | 140 | | |
| R _{DS(ON)} | Static Drain-Source On-Resistance ² $V_{GS} = -4.5V$, $I_D = -6A$ | V _{GS} =-4.5V , I _D =-6A | | 168 | 210 | mΩ | |
| V _{GS(th)} | Gate Threshold Voltage | | -1.0 | | -2.5 | V | |
| $	riangle V_{GS(th)}$ | V _{GS(th)} Temperature Coefficient | —_V _{GS} =V _{DS} , I _D =-250uA | | 5.42 | | mV/°C | |
| | Drain Source Leekage Current | V_{DS} =-48V , V_{GS} =0V , T_J =25°C | | | 1 | uA | |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =-48V , V _{GS} =0V , T _J =150°C | | | 5 | | |
| I _{GSS} | Gate-Source Leakage Current | $V_{GS}=\pm 20V$, $V_{DS}=0V$ | | | ±100 | nA | |
| gfs | Forward Transconductance | V _{DS} =-5V , I _D =-5A | | 5.8 | | S | |
| Qg | Total Gate Charge (-4.5V) | | | 5.85 | | | |
| Q_gs | Gate-Source Charge | V_{DS} =-20V , V_{GS} =-4.5V , I_{D} =-5A | | 2.9 | | nC | |
| Q_gd | Gate-Drain Charge | | | 1.8 | | | |
| T _{d(on)} | Turn-On Delay Time | | | 10 | | | |
| T _r | Rise Time | V_{DD} =-12V , V_{GS} =-10V , R_G =3.3 Ω , | | 17 | | ns | |
| T _{d(off)} | Turn-Off Delay Time | I _D =-5A | | 22 | | | |
| T _f | Fall Time | | | 21 | | | |
| Ciss | Input Capacitance | | | 715 | | | |
| Coss | Output Capacitance | V _{DS} =-15V , V _{GS} =0V , F=1MHz | | 51 | | pF | |
| C _{rss} | Reverse Transfer Capacitance | | | 34 | | | |
| ls | Continuous Source Current ^{1,5} | | | | -9.5 | А | |
| I _{SM} | Pulsed Source Current ^{2,5} | $V_{G}=V_{D}=0V$, Force Current | | | -24 | А | |
| V_{SD} | Diode Forward Voltage ² | V_{GS} =0V , I _S =-1A , T _J =25 $^{\circ}$ C | | | -1.2 | V | |
| t _{rr} | Reverse Recovery Time | | | 10.2 | | nS | |
| Qrr | Reverse Recovery Charge | IF=-8A,dl/dt=100A/μs,Tյ=25℃ | | 5.4 | | nC | |

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2. The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%

3. The EAS data shows Max. rating. The test condition is V_{DD} =-25V, V_{GS} =-10V,L=0.1mH,I_{AS}=-15A

4. The power dissipation is limited by 150°C junction temperature

5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

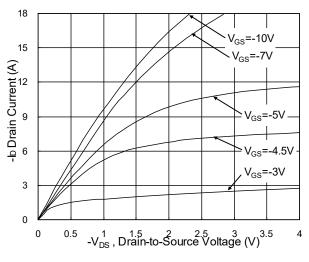


Fig.1 Typical Output Characteristics

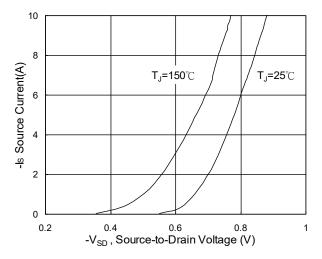
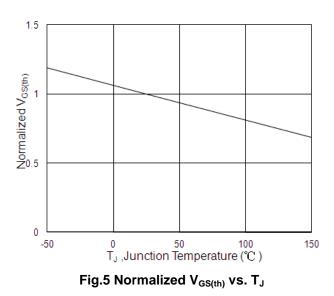


Fig.3 Forward Characteristics Of Reverse



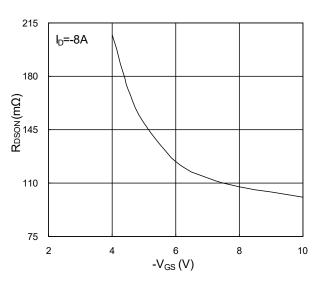


Fig.2 On-Resistance vs. G-S Voltage

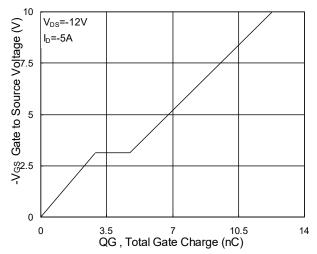


Fig.4 Gate-Charge Characteristics

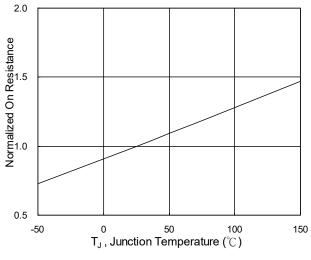
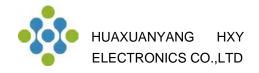
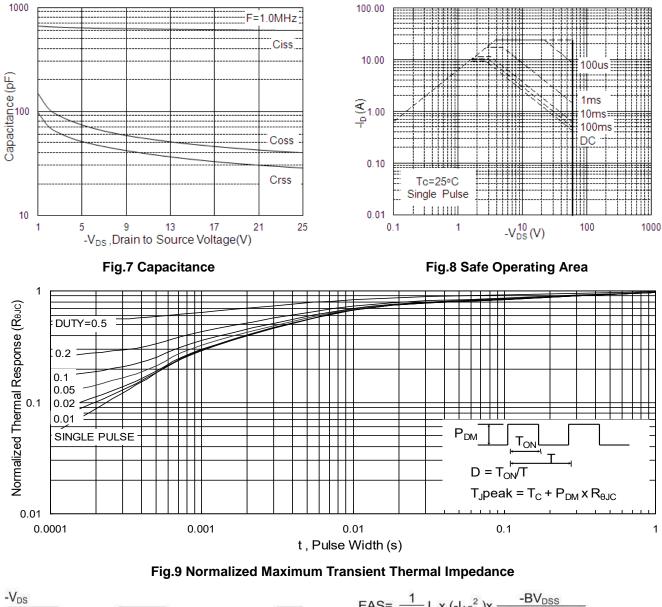


Fig.6 Normalized R_{DSON} vs. T_J





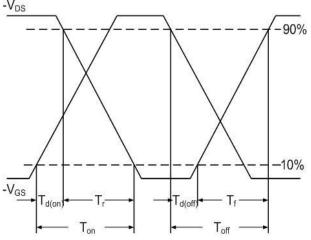


Fig.10 Switching Time Waveform

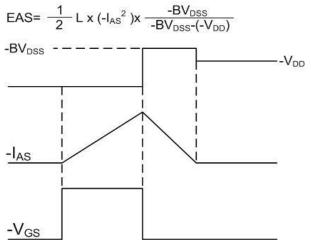
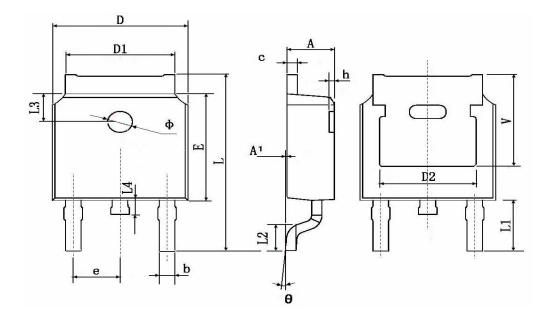


Fig.11 Unclamped Inductive Switching Waveform



TO-252-2L Package Information



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | | |
|--------|---------------------------|--------|----------------------|-------|--|
| | Min. | Max. | Min. | Max. | |
| A | 2.200 | 2.400 | 0.087 | 0.094 | |
| A1 | 0.000 | 0.127 | 0.000 | 0.005 | |
| b | 0.660 | 0.860 | 0.026 | 0.034 | |
| с | 0.460 | 0.580 | 0.018 | 0.023 | |
| D | 6.500 | 6.700 | 0.256 | 0.264 | |
| D1 | 5.100 | 5.460 | 0.201 | 0.215 | |
| D2 | 4.830 TYP. | | 0.190 TYP. | | |
| E | 6.000 | 6.200 | 0.236 | 0.244 | |
| е | 2.186 | 2.386 | 0.086 | 0.094 | |
| L | 9.800 | 10.400 | 0.386 | 0.409 | |
| L1 | 2.900 TYP. | | 0.114 TYP. | | |
| L2 | 1.400 | 1.700 | 0.055 | 0.067 | |
| L3 | |) TYP. | 0.063 TYP. | | |
| L4 | 0.600 | 1.000 | 0.024 | 0.039 | |
| Φ | 1.100 | 1.300 | 0.043 | 0.051 | |
| θ | 0 ° | 8° | 0° | 8° | |
| h | 0.000 | 0.300 | 0.000 | 0.012 | |
| V | 5.350 TYP. | | 0.211 TYP. | | |



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